



Chipsmall Limited consists of a professional team with an average of over 10 year of expertise in the distribution of electronic components. Based in Hongkong, we have already established firm and mutual-benefit business relationships with customers from,Europe,America and south Asia,supplying obsolete and hard-to-find components to meet their specific needs.

With the principle of “Quality Parts,Customers Priority,Honest Operation,and Considerate Service”,our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip,ALPS,ROHM,Xilinx,Pulse,ON,Everlight and Freescale. Main products comprise IC,Modules,Potentiometer,IC Socket,Relay,Connector.Our parts cover such applications as commercial,industrial, and automotives areas.

We are looking forward to setting up business relationship with you and hope to provide you with the best service and solution. Let us make a better world for our industry!



Contact us

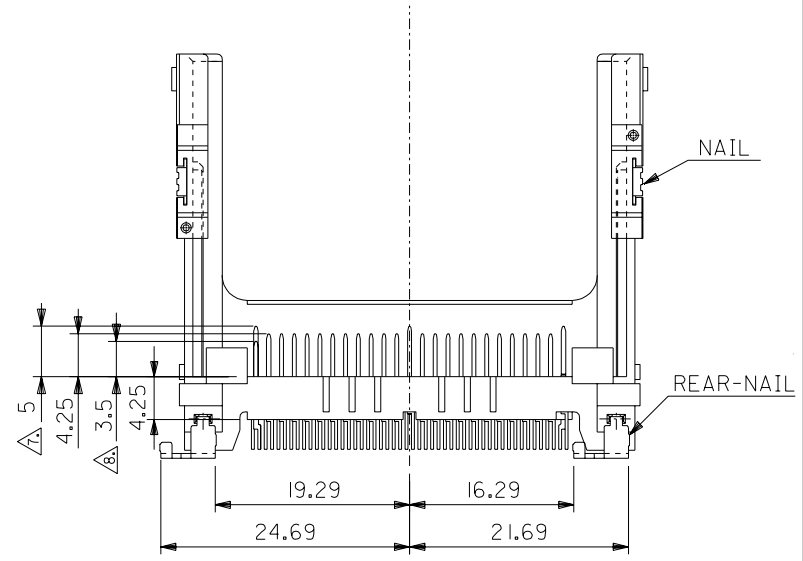
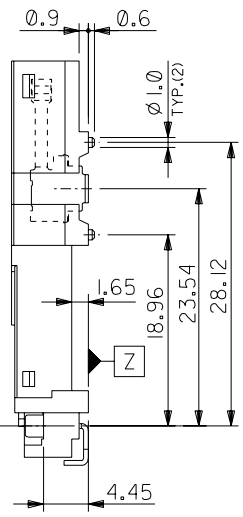
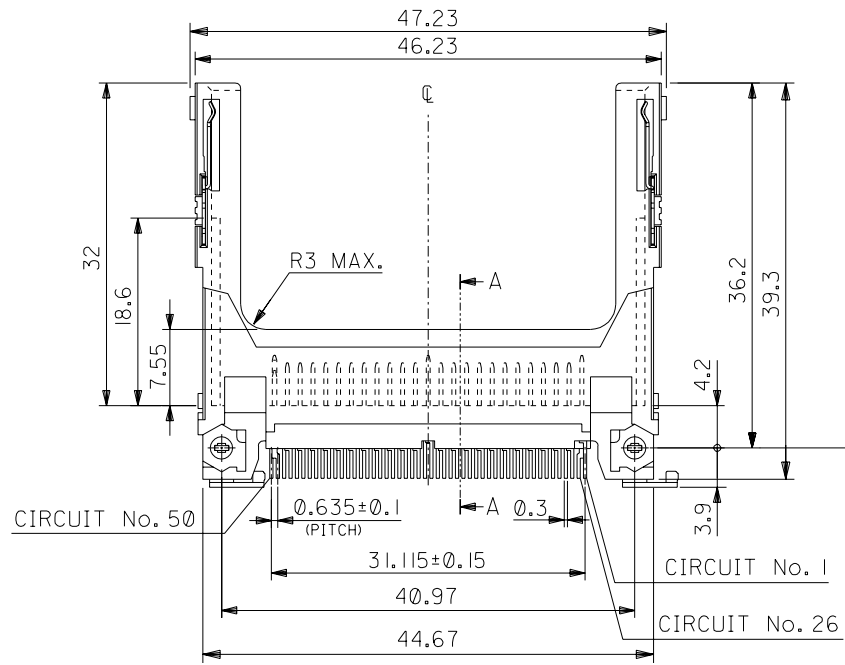
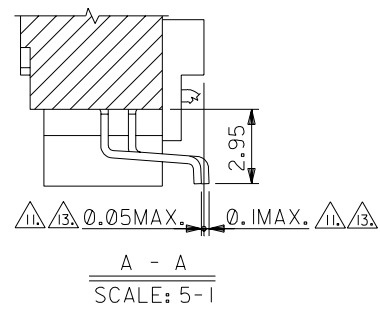
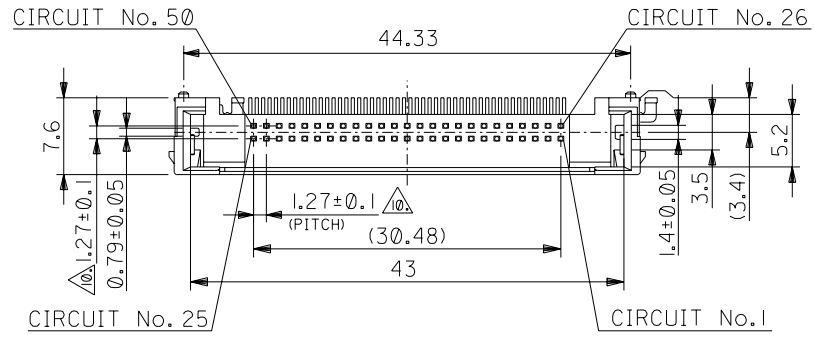
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Address: A1208, Overseas Decoration Building, #122 Zhenhua RD., Futian, Shenzhen, China



DWG. NO. SD-55358-014



DO NOT SCALE DRAWING

| | | | | |
|----------------------------------|----------------------------------|----------------------------------|----------------------------------|--|
| EC NO. DRWN: CHK: APPR: | EC NO. DRWN: CHK: APPR: | EC NO. DRWN: CHK: APPR: | EC NO. DRWN: CHK: APPR: | RELEASED EC NO. J2004-3952 DRWN: M.NABEI '04/04/22 CHK: K.TOJO '04/04/22 APPR: M.SASAO '04/04/22 |
|----------------------------------|----------------------------------|----------------------------------|----------------------------------|--|

| | | | | |
|-------------|----------------|---------------|----------------------|--------------------|
| DESCRIPTION | MATERIAL 材料 | FINISH 仕上り | WIRE RANGE 適用規格範囲 | INS. RANGE 被覆外径 |
| | SEE NOTES | SEE NOTES | # | # |

| | |
|---|-------|
| GENERAL TOLERANCES: (UNLESS SPECIFIED) 一般公差 | |
| 10 UNDER 未満 | ±0.2 |
| 10 OVER 30 UNDER 以上 未満 | ±0.25 |
| 30 OVER 以上 | ±0.3 |
| ANGLE 角度 | ±3° |

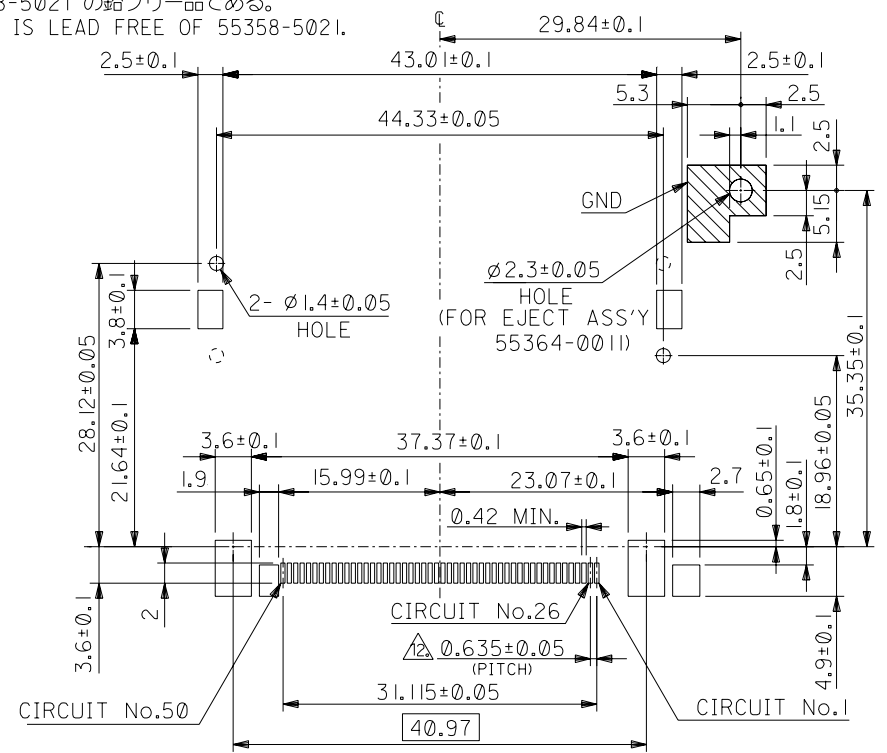
| | | | | | |
|--|--|---|--|---------------------|-----------|
| 55358-5028 | | 55358-5029 | | 55358-50** | |
| HARD TRAY PACKAGE | | MATERIAL No. | | MODEL No. | |
| SCALE 2 - 1 | DESIGN UNITS <input checked="" type="checkbox"/> mm <input type="checkbox"/> INCH | DIMENSIONS: <input type="checkbox"/> mm <input type="checkbox"/> INCH <input type="checkbox"/> mm ONLY | | SHT | REV |
| DRAWN BY & DATE M.NABEI '04/04/22 | | TITLE: CF CARD CONN. 50P HEADER ASS'Y (TYPE I/II, NORMAL) -LEAD FREE- | | | |
| CHECKED BY & DATE K.TOJO '04/04/22 | | MATERIAL NO. SEE CHART | | | |
| APPROVED BY & DATE M. Sasao '04/04/22 | | DRAWING NO. SD-55358-014 | | SHEET NO. 1 OF 2 | |
| CAD FILENAME SD-55358-014.S01 | | | | | |
| THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION. | | | | | |
| | | | | | SIZE B |

SD-55358-014.S01

DWG. NO. SD-55358-014

- 注) 1. 材質 MATERIAL
 ハウジング: ガラス入りLCP UL94V-0
 HOUSING: LIQUID CRYSTAL POLYMER G.F. UL94V-0
 ピン: リン青銅
 PIN: PHOSPHOR BRONZE
 ネール: リン青銅 (t0.3)
 NAIL: PHOSPHOR BRONZE (t0.3)
 リヤネール: リン青銅 (t0.48)
 REAR-NAIL: PHOSPHOR BRONZE (t0.48)
2. メッキ仕様 PLATING
 ピン PIN 接点部: パラジウムニッケル下地、金メッキ
 CONTACT AREA: GOLD OVER PALLADIUM-NICKEL
 半田付け部: 錫メッキ
 SOLDER TAIL AREA: TIN
 下地メッキ: ニッケルメッキ
 UNDERPLATING: NICKEL OVER ALL
 ネール NAIL 接点部: 金メッキ
 CONTACT AREA: GOLD
 半田付け部: 錫メッキ
 SOLDER TAIL AREA: TIN
 下地メッキ: ニッケルメッキ
 UNDERPLATING: NICKEL OVER ALL
 リヤネール REAR-NAIL 錫メッキ
 TIN
 下地メッキ: ニッケルメッキ
 UNDERPLATING: NICKEL OVER ALL
3. 推奨基板厚: t=0.8 MIN.
 RECOMMENDED P.C.B. THICKNESS: t=0.8 MIN.
4. 適合カード厚: 3.3±0.1 (TYPE I) AND 5 MAX. (TYPE II)
 RECOMMENDED CARD THICKNESS: 3.3±0.1 (TYPE I) AND 5 MAX. (TYPE II)
5. 適合カード幅: 42.8±0.1
 RECOMMENDED CARD WIDTH: 42.8±0.1
6. ハウジング色: 黒
 HOUSING COLOR: BLACK
7. 寸法適用極: 1,13,38,50
 THIS DIMENSION APPLIES TO CIRCUIT NUMBERS 1,13,38 AND 50.
8. 寸法適用極: 25,26
 THIS DIMENSION APPLIES TO CIRCUIT NUMBERS 25 AND 26.
9. ピンの倒れは、ピン根元を基準に全方向へ0.1 MAX.とする。
 PIN TIP LEAN TOWARD ANY DIRECTION NOT TO EXCEED 0.1 WHEN MEASURED FROM PIN BASE.
10. ピン根元に適用する。
 THIS DIMENSION TO BE MEASURED AT PIN BASE.

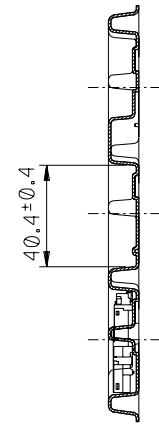
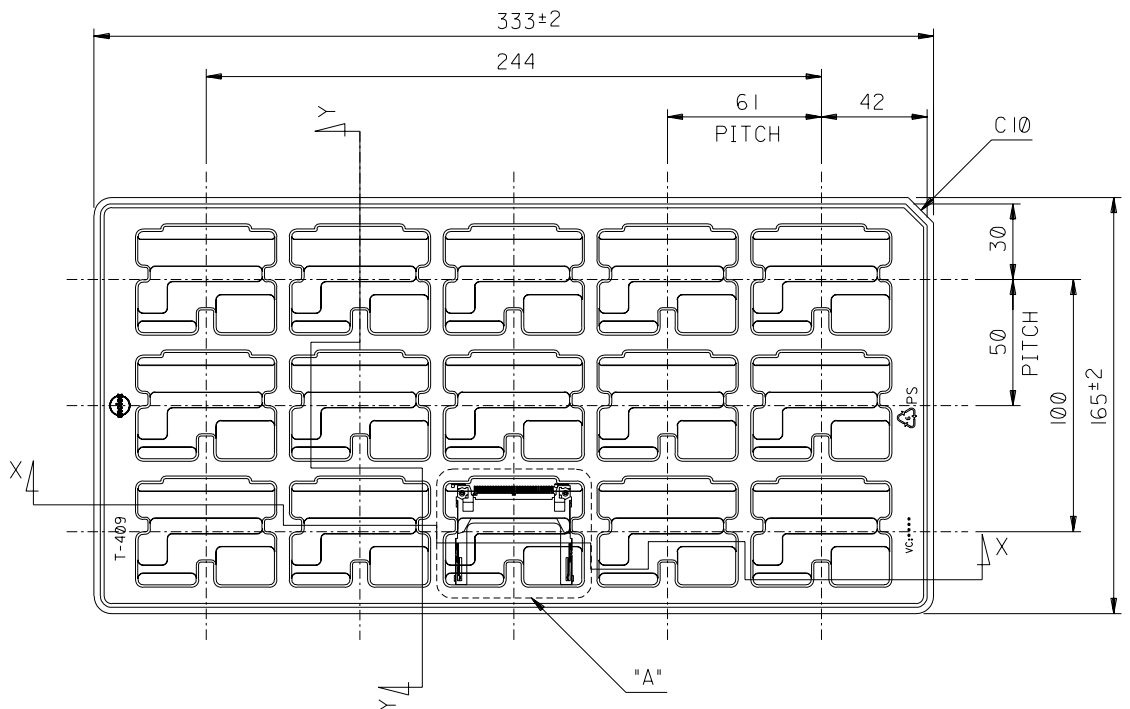
11. ソルダータールは、Z面を基準とし上へ0.05下へ0.1の範囲にあり、且つソルダータールの平坦度は、0.1 MAX.とし、テール先端にて測定する。
 SOLDERTAILS TO BE WITHIN 0.05 UPWARD AND 0.1 DOWNWARD FROM Z-DATUM PLACE, AND COPLANARITY OF SOLDERTAILS TO BE WITHIN 0.1. MEASUREMENT POINT IS SOLDER TAILS TIP.
12. 公差非累積 NON-CUMULATIVE
13. テールとネール、リヤネールを併せた平坦度は、0.1 MAX.とする。
 TOTAL COPLANARITY OF SOLDER TAILS, NAILS AND REAR-NAILS TO BE 0.1 MAX.
14. 本製品は 55358-5021 の鉛フリー品である。
 THIS PRODUCT IS LEAD FREE OF 55358-5021.



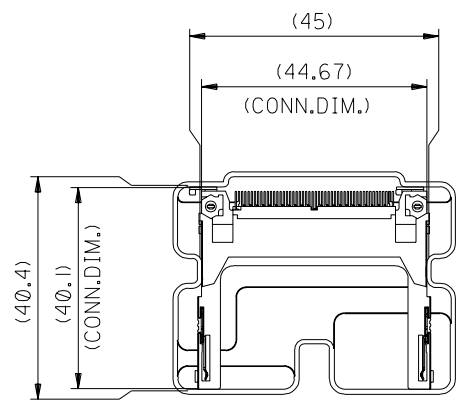
基板推奨寸法
 RECOMMENDED P.C.B. LAYOUT

| | | | | | | | | | | | | | | | | | | | | | | | |
|----------------------|--------------------------|--|--------------------------|--|--------------------------|--|--------------------------|--|--------------------------|--|-----|-------------|---|--|---------------------------------------|--------------|---|------------------------|-------------|---------|-----------|----------------------|--|
| DO NOT SCALE DRAWING | EC NO. DRWN: CH'K: APPR: | | EC NO. DRWN: CH'K: APPR: | | EC NO. DRWN: CH'K: APPR: | | EC NO. DRWN: CH'K: APPR: | | EC NO. DRWN: CH'K: APPR: | | REV | MATERIAL 材料 | GENERAL TOLERANCES: (UNLESS SPECIFIED) 一般公差 | 55358-50** | | MODEL NO. | | DIMENSIONS: | | SHT | REV | | |
| | SEE NOTES | | SEE NOTES | | SEE NOTES | | SEE NOTES | | SEE NOTES | | | | | SCALE 2 - 1 | | DESIGN UNITS | | THIRD ANGLE PROJECTION | | mm INCH | | REVISION ON CAD ONLY | |
| | | | | | | | | | | | | | | | DRAWN BY & DATE M.NABEI '04/04/22 | | TITLE: CF CARD CONN. 50P HEADER ASS'Y (TYPE I/II, NORMAL) -LEAD FREE- | | | | | | |
| | | | | | | | | | | | | | | | CHECKED BY & DATE K.TOJO '04/04/22 | | MOLEX INCORPORATED | | | | | | |
| | | | | | | | | | | | | | | | APPROVED BY & DATE H. Saito '04/04/22 | | MATERIAL NO. | | DRAWING NO. | | SHEET NO. | | |
| | | | | | | | | | | | | | | | CAD FILENAME SD-55358-014.S02 | | DRAWING NO. SD-55358-014 | | SHEET NO. 2 | | SIZE B | | |
| | | | | | | | | | | | | | | THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION. | | | | | | | | | |

DWG. NO. SD-55358-016



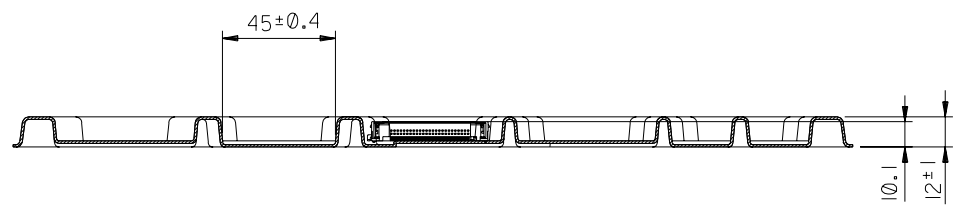
SECT. Y-Y



DETAIL A
(SCALE 1-1)

NOTES

1. 一般公差: ±0.5
GENERAL TOLERANCES: ±0.5
2. 反り: 2MAX.
WARP: 2MAX.
3. 梱包数: 15個
PACKAGING QUANTITY: 15PCS.
4. 本製品は 55358-5026/-5036 の鉛フリー品である。
THIS PRODUCT IS LEAD FREE OF 55358-5026/-5036.



SECT. X-X

| | | | |
|------------------|-------------------------|----------------------|------------|
| 15 | 55358-5039 | 55358-5038 | 50 |
| | 55358-5029 | 55358-5028 | |
| 梱包数量 QUANTITY | コネクタ番号 CONNECTOR No. | 製品番号 MATERIAL No. | 極数 CKT. |

DO NOT SCALE DRAWING

| | | | | | | | | | | |
|---------------------------------|---------------------------------|---------------------------------|---------------------------------|---|---|---|--|--|--|--|
| 64NO. DRWN: CHK: APPR: | 63NO. DRWN: CHK: APPR: | 62NO. DRWN: CHK: APPR: | 61NO. DRWN: CHK: APPR: | RELEASED 60NO. J2004-3952 DRWN: M.NABEI CHK: K.TOJO APPR: M.SASAO | MATERIAL 材料 POLYSTYRENE (t=1.0) | GENERAL TOLERANCES: (UNLESS SPECIFIED) 一般公差 10 UNDER 未満 ±0.2 10 OVER 以上 ±0.25 30 UNDER 未満 ±0.25 30 OVER 以上 ±0.3 ANGLE 角度 ±3° | SCALE 1:2 DESIGN UNITS <input checked="" type="checkbox"/> mm <input type="checkbox"/> INCH | MODEL NO. <input checked="" type="checkbox"/> FIRST ANGLE PROJECTION | DIMENSIONS: <input type="checkbox"/> mm <input type="checkbox"/> INCH <input checked="" type="checkbox"/> mm ONLY | SHT 1 OF 1 REV B |
| | | | | | | | DRAWN BY & DATE M.NABEI '04/04/22 | CHECKED BY & DATE K.TOJO '04/04/22 | APPROVED BY & DATE M.SASAO '04/04/22 | TITLE: TRAY FOR CF CARD CONN. 50P HEADER HS'G ASS'Y -LEAD FREE- |

THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION.

SD-55358-016.S01